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REVISION HISTORY

7/12—Revision 0: Initial Version

SPECIFICATIONS

V_{POS} = 5 V, C_{LPF} = 220 pF, T_A = 25°C, 52.3 Ω termination resistor at INHI, unless otherwise noted.

Table 1.

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
SIGNAL INPUT INTERFACE	INHI (Pin 14) and INLO (Pin 15)				
Specified Frequency Range		0.001		8	GHz
DC Common-Mode Voltage			V_{POS} − 1.8		V
MEASUREMENT MODE	VOUT (Pin 6) shorted to VSET (Pin 7), sinusoidal input signal				
f = 900 MHz	R_{TADJ} = 500 Ω				
Input Impedance			957||0.71		Ω||pF
±3 dB Dynamic Range	T_A = 25°C		65		dB
	−55°C < T_A < +105°C		63		dB
±1 dB Dynamic Range	T_A = 25°C		57		dB
Maximum Input Level	±1 dB error		−1		dBm
Minimum Input Level	±1 dB error		−58		dBm
Slope		−26	−24.5	−23	mV/dB
Intercept		19.5	22	24	dBm
Output Voltage—High Power In	P_{IN} = −10 dBm	0.7	0.78	0.86	V
Output Voltage—Low Power In	P_{IN} = −40 dBm	1.42	1.52	1.62	V
Temperature Sensitivity	P_{IN} = −10 dBm				
	25°C ≤ T_A ≤ 105°C		0.0071		dB/°C
	−55°C ≤ T_A ≤ +25°C		0.0031		dB/°C
f = 1.9 GHz	R_{TADJ} = 500 Ω				
Input Impedance			523||0.68		Ω||pF
±3 dB Dynamic Range	T_A = 25°C		65		dB
	−55°C < T_A < +105°C		63		dB
±1 dB Dynamic Range	T_A = 25°C		57		dB
Maximum Input Level	±1 dB error		−2		dBm
Minimum Input Level	±1 dB error		−59		dBm
Slope		−27	−24.4	−22	mV/dB
Intercept		17	20.4	24	dBm
Output Voltage—High Power In	P_{IN} = −10 dBm	0.63	0.73	0.83	V
Output Voltage—Low Power In	P_{IN} = −35 dBm	1.2	1.35	1.5	V
Temperature Sensitivity	P_{IN} = −10 dBm				
	25°C ≤ T_A ≤ 105°C		0.0056		dB/°C
	−55°C ≤ T_A ≤ +25°C		0.0004		dB/°C
f = 2.2 GHz	R_{TADJ} = 500 Ω				
Input Impedance			391||0.66		Ω||pF
±3 dB Dynamic Range	T_A = 25°C		65		dB
	−55°C < T_A < +105°C		62		dB
±1 dB Dynamic Range	T_A = 25°C		58		dB
Maximum Input Level	±1 dB error		−2		dBm
Minimum Input Level	±1 dB error		−60		dBm
Slope		−28	−24.4	−21.5	mV/dB
Intercept		15	19.6	25	dBm
Output Voltage—High Power In	P_{IN} = −10 dBm	0.63	0.73	0.84	V
Output Voltage—Low Power In	P_{IN} = −35 dBm	1.2	1.34	1.5	V
Temperature Sensitivity	P_{IN} = −10 dBm				
	25°C ≤ T_A ≤ 105°C		0.0052		dB/°C
	−55°C ≤ T_A ≤ +25°C		0.0034		dB/°C

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
f = 3.6 GHz	R_{TADJ} = 51 Ω				
Input Impedance			119||0.7		Ω||pF
±3 dB Dynamic Range	T_A = 25°C		70		dB
	−55°C < T_A < +105°C		61		dB
±1 dB Dynamic Range	T_A = 25°C		58		dB
Maximum Input Level	±1 dB error		−2		dBm
Minimum Input Level	±1 dB error		−60		dBm
Slope			−24.3		mV/dB
Intercept			19.8		dBm
Output Voltage—High Power In	P_{IN} = −10 dBm		0.717		V
Output Voltage—Low Power In	P_{IN} = −40 dBm		1.46		V
Temperature Sensitivity	P_{IN} = −10 dBm				
	25°C ≤ T_A ≤ 105°C		0.0012		dB/°C
	−55°C ≤ T_A ≤ +25°C		0.009		dB/°C
f = 5.8 GHz	R_{TADJ} = 1000 Ω				
Input Impedance			33||0.59		Ω||pF
±3 dB Dynamic Range	T_A = 25°C		70		dB
	−55°C < T_A < +105°C		62		dB
±1 dB Dynamic Range	T_A = 25°C		57		dB
Maximum Input Level	±1 dB error		−1		dBm
Minimum Input Level	±1 dB error		−58		dBm
Slope			−24.3		mV/dB
Intercept			25		dBm
Output Voltage—High Power In	P_{IN} = −10 dBm		0.86		V
Output Voltage—Low Power In	P_{IN} = −40 dBm		1.59		V
Temperature Sensitivity	P_{IN} = −10 dBm				
	25°C ≤ T_A ≤ 105°C		0.019		dB/°C
	−55°C ≤ T_A ≤ +25°C		0.0096		dB/°C
f = 8.0 GHz	R_{TADJ} = 500 Ω				
±3 dB Dynamic Range	T_A = 25°C		60		dB
	−55°C < T_A < +105°C		58		dB
Maximum Input Level	±3 dB error		3		dBm
Minimum Input Level	±3 dB error		−55		dBm
Slope			−23		mV/dB
Intercept			37		dBm
Output Voltage—High Power In	P_{IN} = −10 dBm		1.06		V
Output Voltage—Low Power In	P_{IN} = −40 dBm		1.78		V
Temperature Sensitivity	P_{IN} = −10 dBm				
	25°C ≤ T_A ≤ 105°C		0.032		dB/°C
	−55°C ≤ T_A ≤ +25°C		0.0078		dB/°C
OUTPUT INTERFACE	VOUT (Pin 6)				
Voltage Swing	V_{SET} = 0 V; P_{IN} = −10 dBm, no load[1]		4.9		V
	V_{SET} = 2.1 V; P_{IN} = −10 dBm, no load[1]		25		mV
Output Current Drive	V_{SET} = 1.5 V; P_{IN} = −50 dBm		60		mA
Small Signal Bandwidth	P_{IN} = −10 dBm; from CLPF to VOUT		60		MHz
Video Bandwidth (or Envelope Bandwidth)			45		MHz
Output Noise	P_{IN} = 2.2 GHz; −10 dBm, f_{NOISE} = 100 kHz, C_{LPF} = 220 pF		90		nV/√Hz
Fall Time	P_{IN} = Off to −10 dBm, 90% to 10%		10		ns
Rise Time	P_{IN} = −10 dBm to off, 10% to 90%		12		ns

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
VSET INTERFACE	VSET (Pin 7)				
Nominal Input Range	P_{IN} = 0 dBm; measurement mode[2]		0.5		
	P_{IN} = −65 dBm; measurement mode[2]		2.1		V
Logarithmic Scale Factor			−0.04		dB/mV
Bias Current Source	P_{IN} = −10 dBm; V_{SET} = 2.1 V		2.5		µA
TEMPERATURE REFERENCE	TEMP (Pin 13)				
Output Voltage	T_A = 25°C, R_{LOAD} = 10 kΩ	0.57	0.6	0.63	V
Temperature Slope	−55°C ≤ T_A ≤ +105°C, R_{LOAD} = 10 kΩ		2		mV/°C
Current Source/Sink	T_A = 25°C		10/0.1		mA
POWER-DOWN INTERFACE	ENBL (Pin 16)				
Logic Level to Enable Device			1.7		V
ENBL Current When Enabled	ENBL = 5 V		<1		µA
ENBL Current When Disabled	ENBL = 0 V; sourcing		15		µA
POWER INTERFACE	VPSI (Pin 3 and Pin 4), VPSO (Pin 9)				
Supply Voltage		4.5	5	5.5	V
Quiescent Current	ENBL = 5 V	50	68	82	mA
vs. Temperature	−55°C ≤ T_A ≤ +105°C		150		µA/°C
Supply Current when Disabled	ENBL = 0 V, total currents for VPSI and VPSO		260		µA
vs. Temperature	−55°C ≤ T_A ≤ +105°C		350		µA

[1] Controller mode.
[2] Gain = 1. For other gains, see the AD8318 data sheet.

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Supply Voltage: Pin VPSO, Pin VPSI	5.7 V
ENBL, V_{SET} Voltage	0 to V_{POS}
Input Power (Single-Ended, re: 50 Ω)	12 dBm
Internal Power Dissipation	0.73 W
θ_{JA} [1]	55°C/W
Maximum Junction Temperature	130°C
Operating Temperature Range	−55°C to +105°C
Storage Temperature Range	−65°C to +150°C

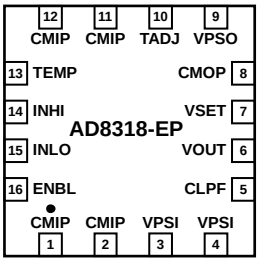
[1] With package die paddle soldered to thermal pads with vias connecting to inner and bottom layers.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES
1. THE EXPOSED PADDLE IS INTERNALLY CONNECTED TO CMIP (SOLDER TO GROUND).

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Figure 3. Pin Configuration

Table 3. Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 2, 11, 12	CMIP	Device Common (Input System Ground).
3, 4	VPSI	Positive Supply Voltage (Input System): 4.5 V to 5.5 V. Voltage on Pin 3, Pin 4, and Pin 9 should be equal.
5	CLPF	Loop Filter Capacitor.
6	VOUT	Measurement and Controller Output.
7	VSET	Setpoint Input for Controller Mode or Feedback Input for Measurement Mode.
8	CMOP	Device Common (Output System Ground).
9	VPSO	Positive Supply Voltage (Output System): 4.5 V to 5.5 V. Voltage on Pin 3, Pin 4, and Pin 9 should be equal.
10	TADJ	Temperature Compensation Adjustment.
13	TEMP	Temperature Sensor Output.
14	INHI	RF Input. Nominal input range: −60 dBm to 0 dBm (re: 50 Ω), ac-coupled.
15	INLO	RF Common for INHI. AC-coupled RF common.
16	ENBL	Device Enable. Connect to VPSI for normal operation. Connect pin to ground for disable mode.
	Paddle	The Exposed Paddle is Internally Connected to CMIP (Solder to Ground).

TYPICAL PERFORMANCE CHARACTERISTICS

V_{POS} = 5 V; T_A = +25°C, −55°C, +105°C; C_{LPF} = 220 pF; R_{TADJ} = 500 Ω; unless otherwise noted. Colors: +25°C → Black; −55°C → Blue; +105°C → Red.

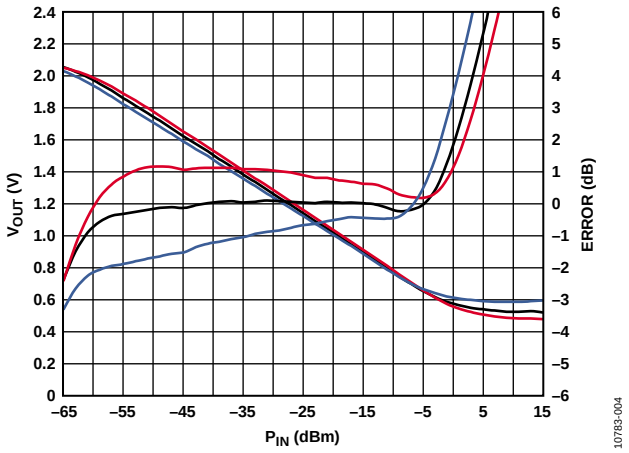

Figure 4. VOUT and Log Conformance vs. Input Amplitude at 900 MHz, Typical Device

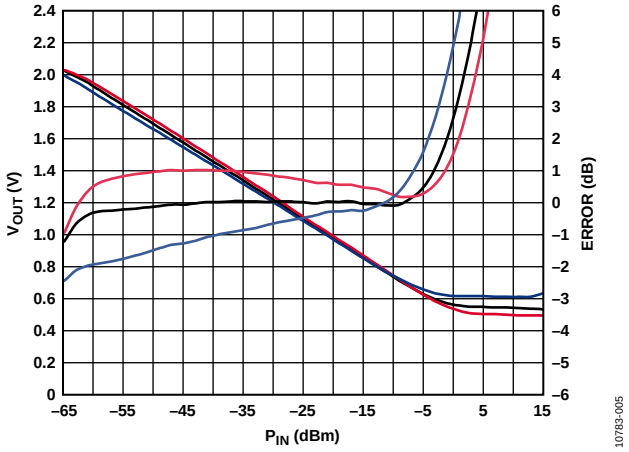

Figure 5. VOUT and Log Conformance vs. Input Amplitude at 1.9 GHz, Typical Device

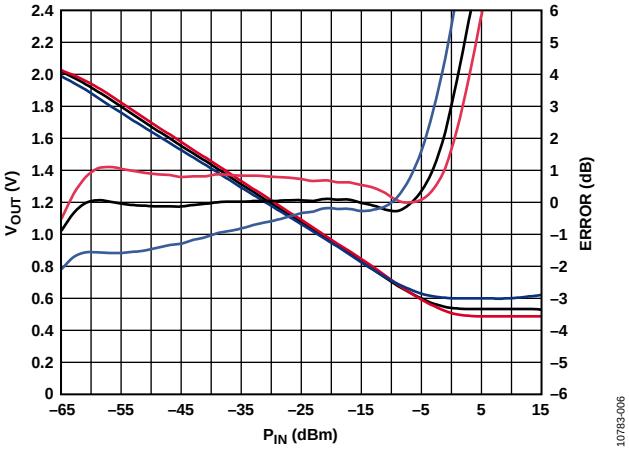

Figure 6. V_{OUT} and Log Conformance vs. Input Amplitude at 2.2 GHz, Typical Device

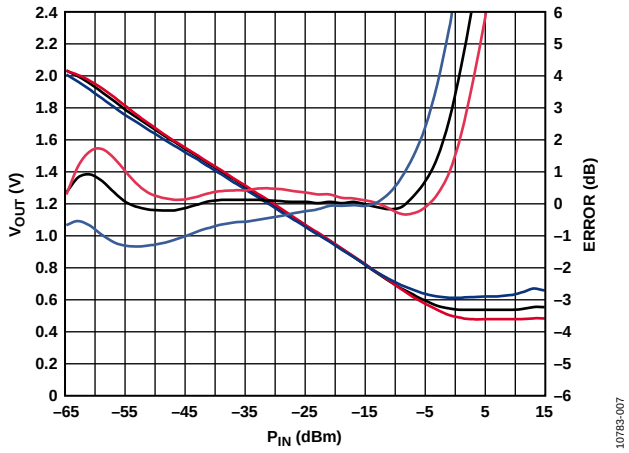

Figure 7. V_{OUT} and Log Conformance vs. Input Amplitude at 3.6 GHz, Typical Device, R_{TADJ} = 51 Ω

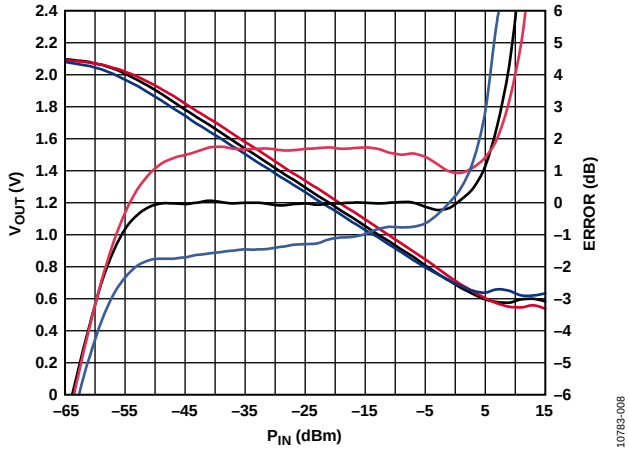

Figure 8. VOUT and Log Conformance vs. Input Amplitude at 5.8 GHz, Typical Device, R_{TADJ} = 1000 Ω

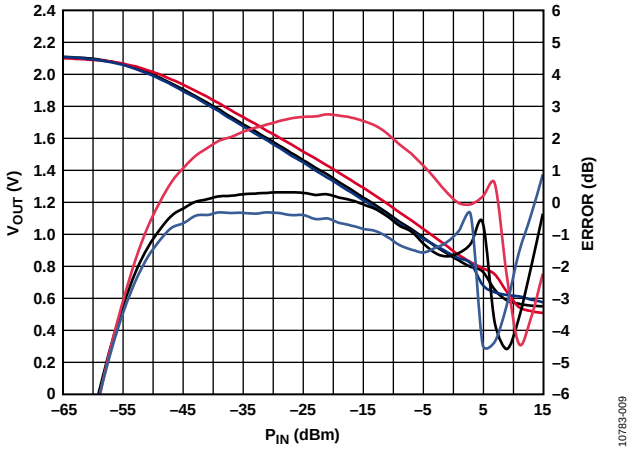

Figure 9. V_{OUT} and Log Conformance vs. Input Amplitude at 8 GHz, Typical Device

V_{POS} = 5 V; T_A = +25°C, −55°C, +105°C; C_{LPF} = 220 pF; R_{TADJ} = 500 Ω; unless otherwise noted. Colors: +25°C → Black; −55°C → Blue; +105°C → Red.

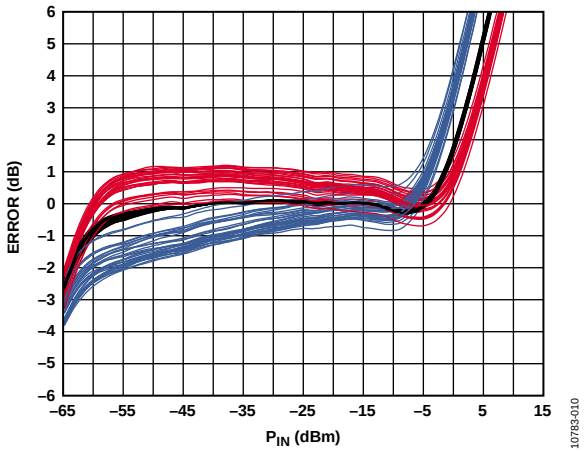

Figure 10. Distribution of Error over Temperature After Ambient Normalization vs. Input Amplitude at 900 MHz for at Least 70 Devices

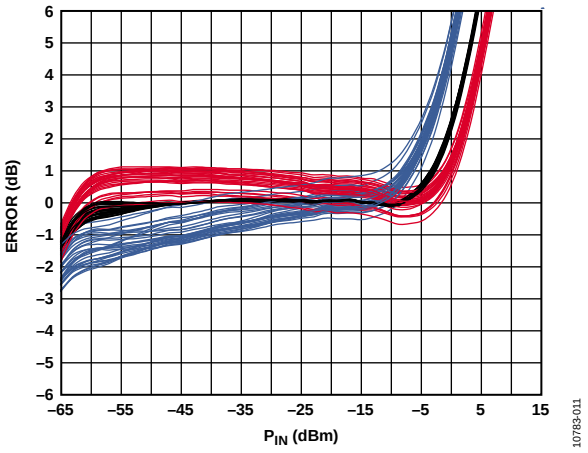

Figure 11. Distribution of Error at Temperature After Ambient Normalization vs. Input Amplitude at 1900 MHz for at Least 70 Devices

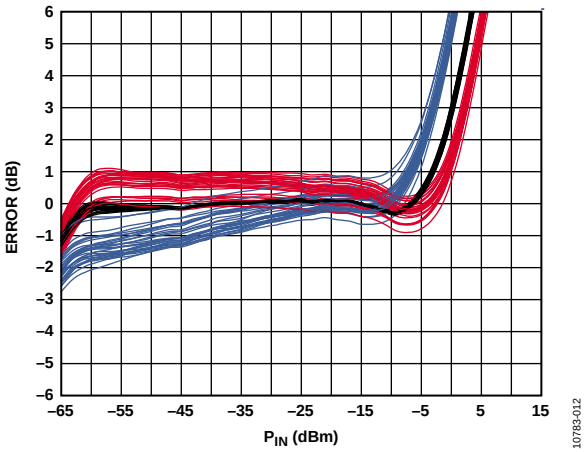

Figure 12. Distribution of Error at Temperature After Ambient Normalization vs. Input Amplitude at 2.2 GHz for at Least 70 Devices

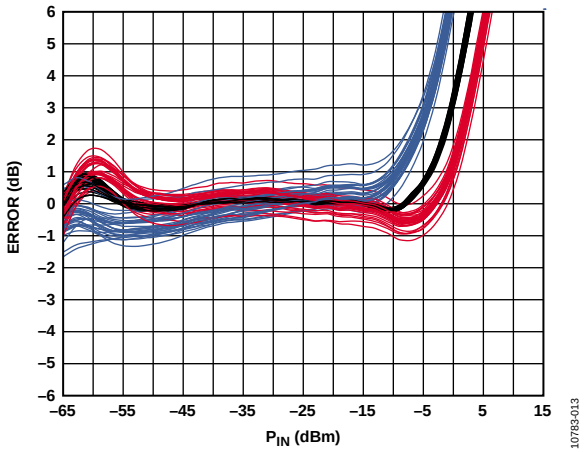

Figure 13. Distribution of Error at Temperature After Ambient Normalization vs. Input Amplitude at 3.6 GHz for at Least 70 Devices, R_{TADJ} = 51 Ω

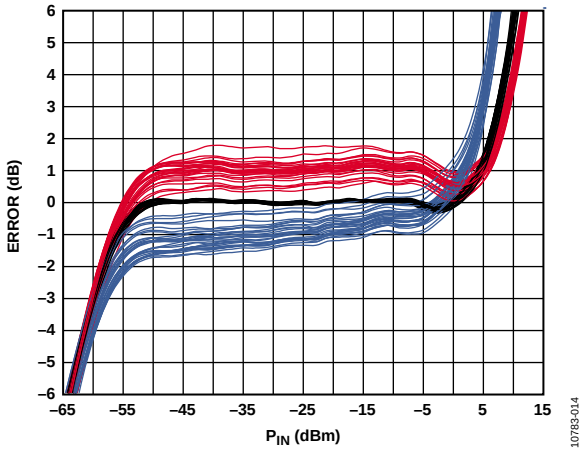

Figure 14. Distribution of Error at Temperature After Ambient Normalization vs. Input Amplitude at 5.8 GHz for at Least 70 Devices, R_{TADJ} = 1000 Ω

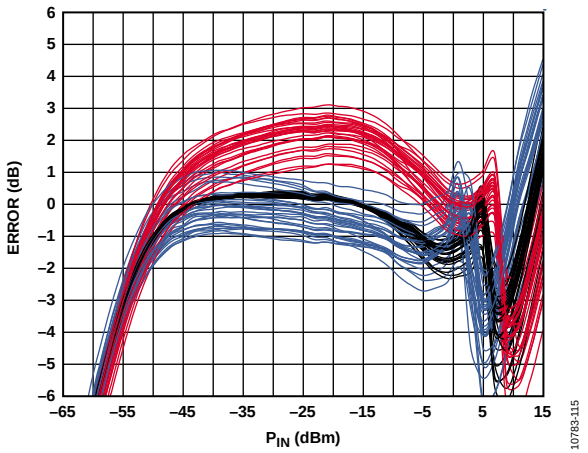

Figure 15. Distribution of Error at Temperature After Ambient Normalization vs. Input Amplitude at 8 GHz for at Least 70 Devices

V_{POS} = 5 V; T_A = +25°C, −55°C, +105°C; C_{LPF} = 220 pF; R_{TADJ} = 500 Ω; unless otherwise noted. Colors: +25°C → Black; −55°C → Blue; +105°C → Red.

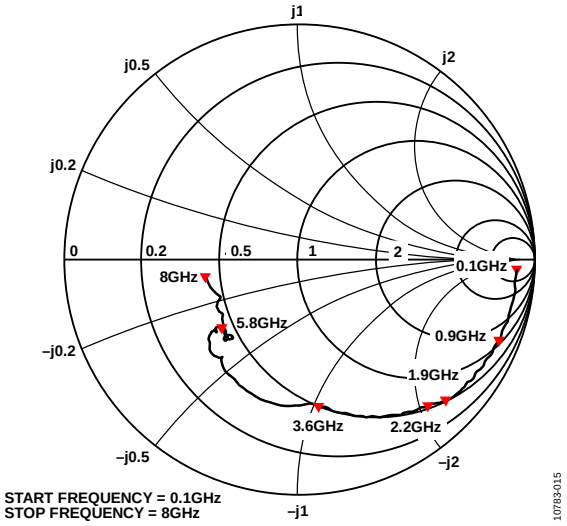

Figure 16. Input Impedance vs. Frequency; No Termination Resistor on INHI, Z_O = 50 Ω

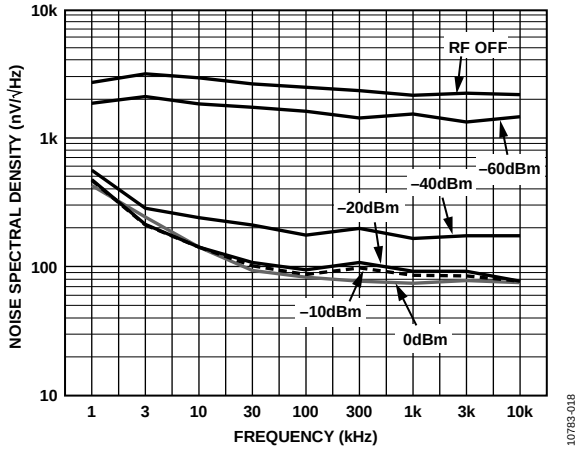

Figure 19. Noise Spectral Density of Output; CLPF = Open

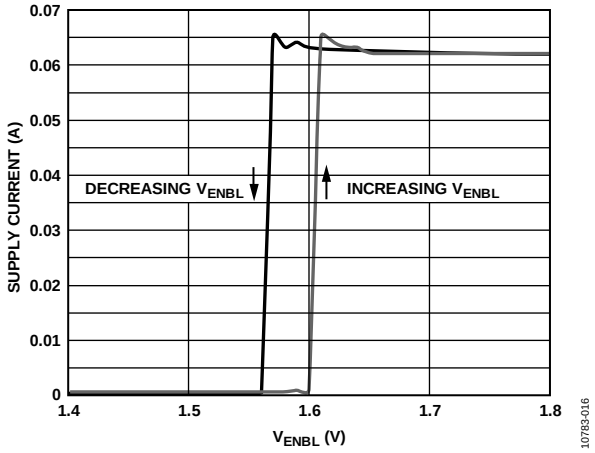

Figure 17. Supply Current vs. Enable Voltage

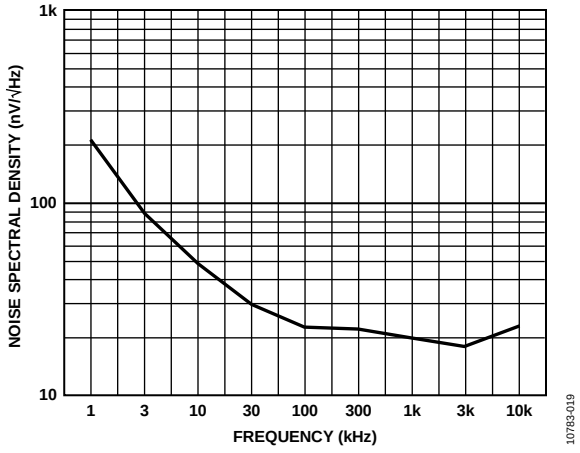

Figure 20. Noise Spectral Density of Output Buffer (from CLPF to VOUT); CLPF = 0.1 µF

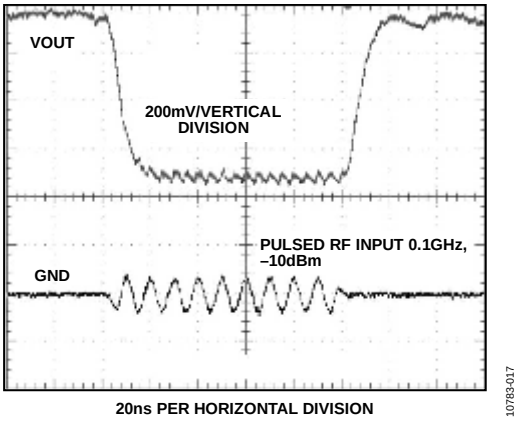

Figure 18. VOUT Pulse Response Time; Pulsed RF Input 0.1 GHz, −10 dBm; CLPF = Open

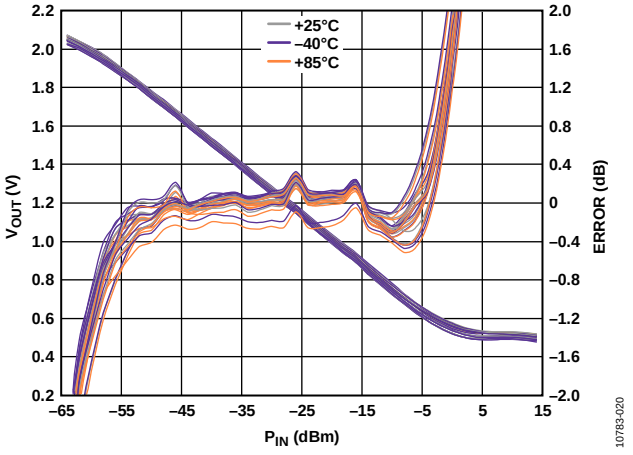

Figure 21. Output Voltage Stability vs. Supply Voltage at 1.9 GHz When VP Varies by 10%, Multiple Devices

OUTLINE DIMENSIONS

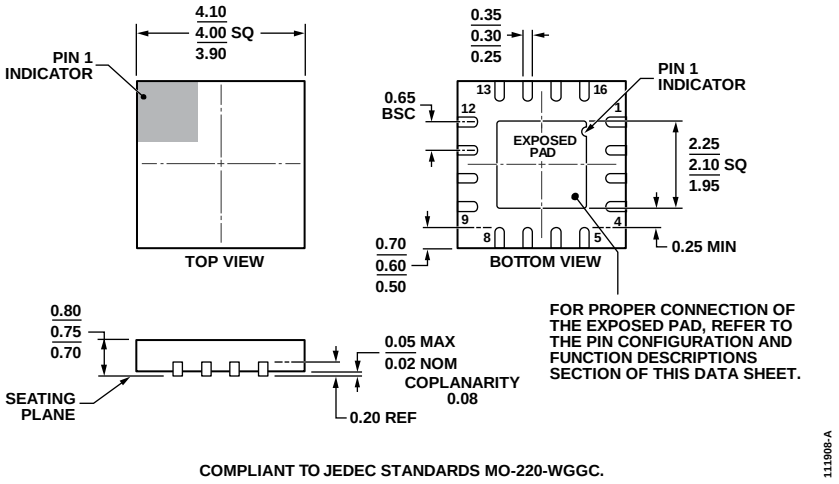

Figure 22. 16-Lead Lead Frame Chip Scale Package [LFCSP_WQ]
4 mm × 4 mm Body, Very Very Thin Quad
(CP-16-23)
Dimensions shown in millimeters

ORDERING GUIDE

Model[1, 2]	Temperature Range	Package Description	Package Option	Ordering Quantity
AD8318SCPZ-EP-RL7	−55°C to +105°C	16-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-16-23	1,500
AD8318SCPZ-EP-R2	−55°C to +105°C	16-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-16-23	250
AD8318SCPZ-EP-WP	−55°C to +105°C	16-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-16-23	64
AD8318-EP-EVALZ		Evaluation Board		

[1] Z = RoHS Compliant Part.
[2] WP = waffle pack.

NOTES